



3D Packaging & Integration North America TC Chapter

NA Standards Summer Meeting 2021

Thursday, July 15

13:30–14:30 (Pacific) via Virtual Meeting

AGENDA

	Time
1 Welcome/Call to Order	13:30
1.1 Log into svm.semi.org for voting	
1.2 Agenda Review	
1.3 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.4 Introductions	
2 Liaison Reports	13:40
2.1 Japan TC Chapter	
2.2 Taiwan TC Chapter	
3 Staff Report	13:45
4 Review of Previous Meeting Minutes	13:50
5 Ballot Review	13:55
5.1 Document R6641 — Revision to SEMI 3D8-0514, Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process	
5.2 Document 6810 — Reapproval of SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks	
5.3 Document 6811 — Reapproval of SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications	
5.4 Document 6812 — Reapproval of SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks	



	Time
6 Task Force Reports	14:15
6.1 3DP&I Bonded Wafer Stacks Task Force	
6.2 3DP&I Inspection & Metrology Task Force	
6.3 Panel Level Packaging (PLP) Panel Task Force	
7 Old Business	14:20
8 New Business	14:25
9 Action Item Review	14:25
9.1 Open Action Items (None)	
9.2 New Action Items	
10 Next Meeting and Adjournment	14:30
10.1 The next meeting is tentatively scheduled for the week of December 6-9, in conjunction with SEMICON West 2021. Schedule details TBD. Please check www.semiconwest.org for updates.	

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NOTE:

Standards meetings are open to all, but you must be a SEMI Standards Program Member to attend.

If you are not a Member, please register for the International SEMI Standards Program here:

<https://www.semi.org/standardsmembership>

Standards Virtual Meeting Information

You must log into BOTH applications listed below

1) Open RingCentral Web Meeting Information below and choose option A, B, or C.

For the best audio experience, please use computer audio.

A. Join by launching the RingCentral App on your computer:

<https://meetings.ringcentral.com/j/1495793447>

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C. Join by Telephone:

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International numbers available: <https://meetings.ringcentral.com/teleconference>

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2) For Voting: Log into the SVM Software by following the instructions below.

1. Open a separate Web browser and go to: <https://svm.semi.org/>
(Do not use Internet Explorer or MS Edge. There are known issues with these browsers)
2. Click "Login"
3. Enter your Standards Membership username and password (same login for voting on ballots)
4. If you have forgotten your password, select "Don't remember your password?" to reset it.
5. Find the meeting room under "Room Name": **3DP&I NA TC Chapter Summer Meeting 2021**
6. Click "Go" to enter the meeting room.